

Figure PZ1 Typical Application Block Diagram for PolyZen Devices

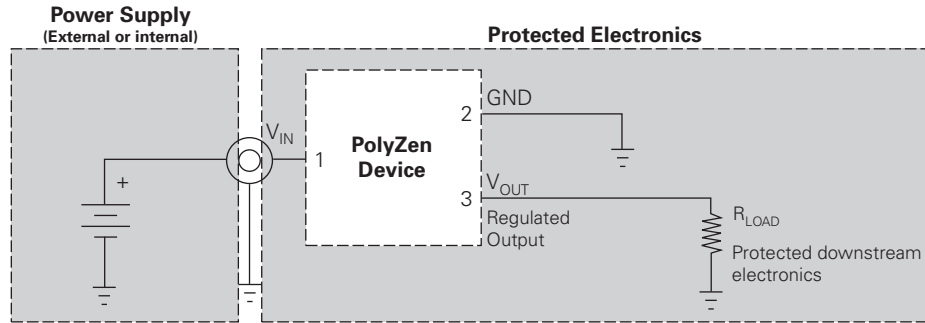


Table PZ1 Electrical Characteristics for PolyZen Devices

(Performance ratings @ 25°C unless otherwise specified)

Part Number	V _Z (V)			I _{Zt} (A)	I _{HOLD} @ 20°C (A)	R _{Typ} (Ω)	R _{1MAX} (Ω)	V _{INT MAX}		I _{FLT MAX}	
	Min.	Typ.	Max.					V _{INT MAX} (V)	Test Current (A)	I _{FLT MAX} (A)	Test Voltage (V)
ZEN056V130A24LS	5.45	5.60	5.75	0.10	1.30	0.12	0.16	24V	3A	+10/-40	+24/-16V
ZEN059V130A24LS†	5.80	5.90	6.00	0.10	1.30	0.12	0.15	24V	3A	+6/-40	+24/-16V
ZEN065V130A24LS	6.35	6.50	6.65	0.10	1.30	0.12	0.16	24V	3A	+6/-40	+24/-16V
ZEN098V130A24LS	9.60	9.80	10.00	0.10	1.30	0.12	0.16	24V	3A	+3.5/-40	+24/-16V
ZEN132V130A24LS	13.20	13.40	13.60	0.10	1.30	0.12	0.16	24V	3A	+2/-40	+24/-16V
ZEN164V130A24LS	16.10	16.40	16.60	0.10	1.30	0.12	0.16	24V	3A	+1.25/-40	+24/-16V
ZEN056V230A16LS	5.45	5.60	5.75	0.10	2.30	0.04	0.06	16V	5A	+5/-40	+16/-12V
ZEN065V230A16LS	6.35	6.50	6.65	0.10	2.30	0.04	0.06	16V	5A	+3.5/-40	+16/-12V
ZEN098V230A16LS	9.60	9.80	10.00	0.10	2.30	0.04	0.06	16V	5A	+3.5/-40	+16/-12V
ZEN132V230A16LS	13.20	13.40	13.60	0.10	2.30	0.04	0.06	16V	5A	+2/-40	+20/-12V
ZEN056V075A48LS	5.45	5.60	5.75	0.10	0.75	0.28	0.45	48V	3A	+10/-40	+48/-16V
ZEN132V075A48LS	13.20	13.40	13.60	0.10	0.75	0.28	0.45	48V	3A	+2/-40	+48/-16V
ZEN056V115A24LS	5.45	5.60	5.75	0.10	1.15	0.15	0.18	24V	3A	+10/-40	+24/-16V
ZEN056V130A24GS*	5.45	5.60	5.75	0.10	1.30	0.12	0.18	24V	3A	+6/-40	+24/-16V

* Module height is 1.25mm. Module height of all other part numbers is 2.0mm.

† Typical operating current is 500µA @ 5.0V which meets USB suspend mode requirement.

Table PZ2 Definitions of Terms for PolyZen Devices

V _Z	Zener clamping voltage measured at current I _{Zt} and 20°C.
I _{Zt}	Test current at which V _Z is measured.
I _{HOLD}	Maximum steady state current I _{PTC} that will not generate a trip event at the specified temperature. Ratings assume I _{FLT} = 0A.
R _{Typ}	Typical resistance between V _{IN} and V _{OUT} pins when the device is at room temperature.
R _{1MAX}	The maximum resistance between V _{IN} and V _{OUT} pins, at room temperature, one hour after first trip or after reflow soldering.
I _{FLT}	Current flowing through the Zener diode.
I _{FLT MAX}	Maximum RMS fault current the Zener diode component of the device can withstand and remain resettable; testing is conducted at rated voltage with no load connected to V _{OUT} .
V _{INT MAX}	The voltage (V _{IN} - V _{OUT} "post trip") at which typical qualification devices (98% devices, 95% confidence) survived at least 100 trip cycles and 24 hours trip endurance when "tripped" at the specified voltage and current (I _{PTC}).
I _{PTC}	Current flowing through the PTC portion of the circuit.
I _{OUT}	Current flowing out the V _{OUT} pin of the device.
Trip Event	A condition where the PTC transitions to a high resistance state, thereby limiting I _{PTC} , and significantly increasing the voltage drop between V _{IN} and V _{OUT} .

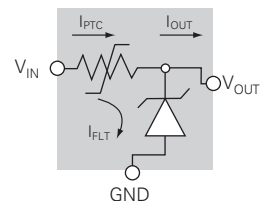
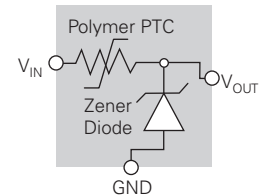


Figure PZ2-PZ9 Typical Performance Curves for PolyZen Devices

Figure PZ2

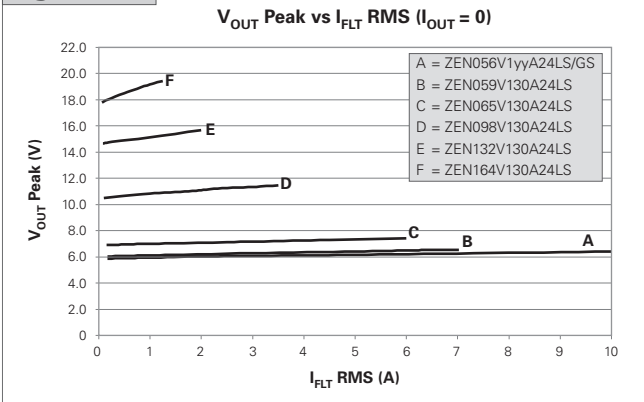


Figure PZ3

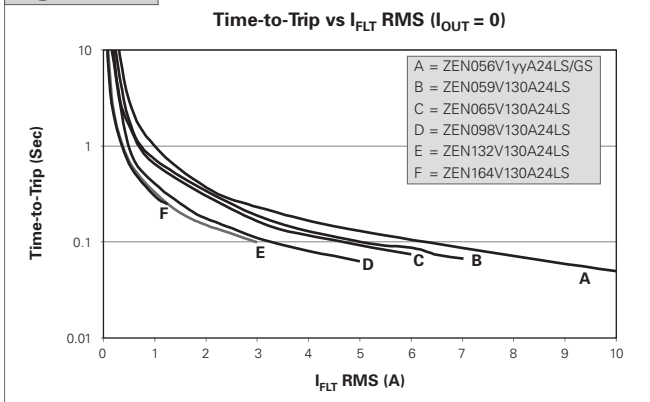


Figure PZ4

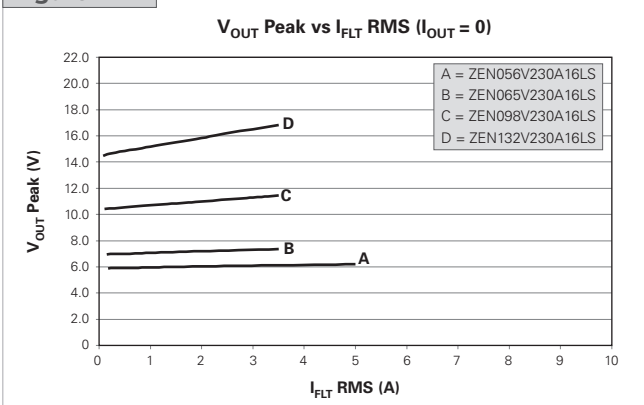


Figure PZ5

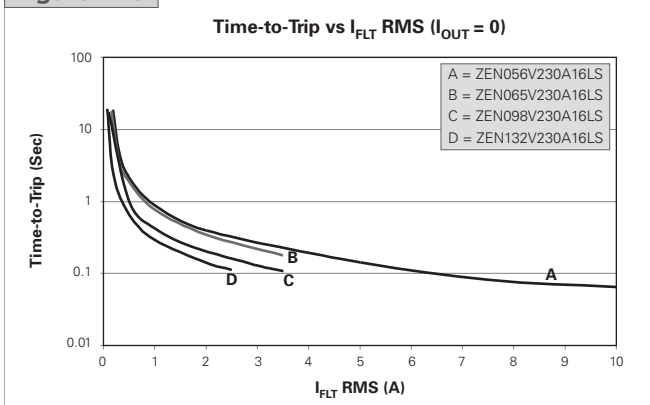


Figure PZ6

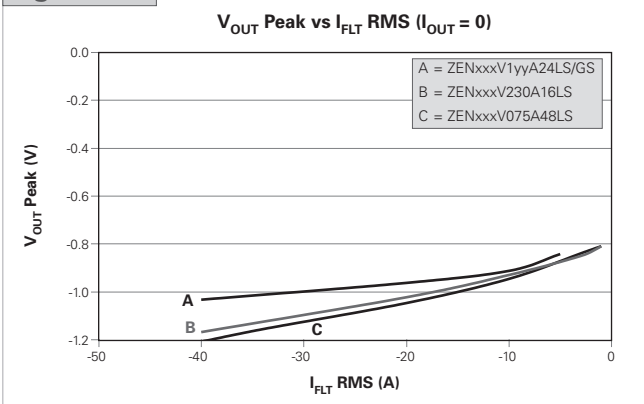


Figure PZ7

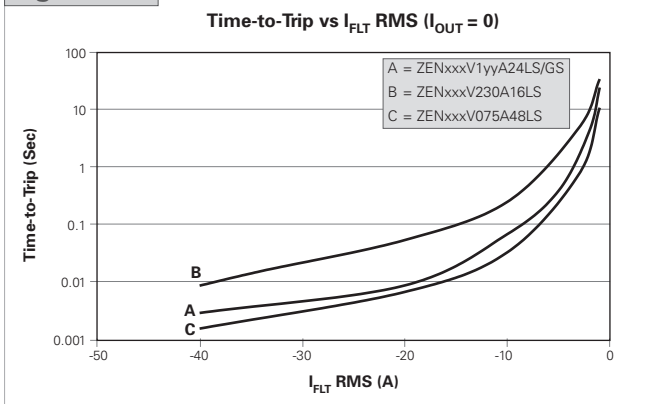


Figure PZ8

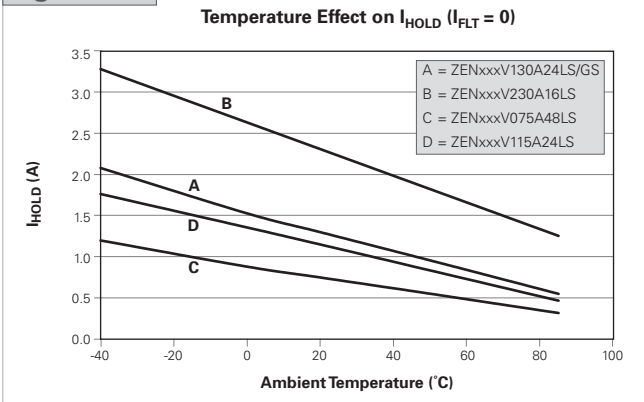


Figure PZ9

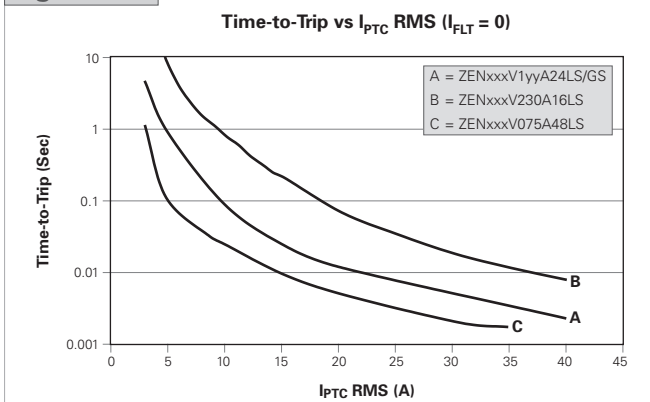


Table PZ3 General Characteristics for PolyZen Devices

Operating temperature range	-40° to +85°C	
Storage temperature	-40° to +85°C	
ESD withstand	15kV	Human body model
Diode capacitance	4200pF	Typical @ 1MHz, 1V RMS
Construction	RoHS compliant	

Figure PZ10-PZ23 Basic Operation Examples for PolyZen Devices

Figure PZ10

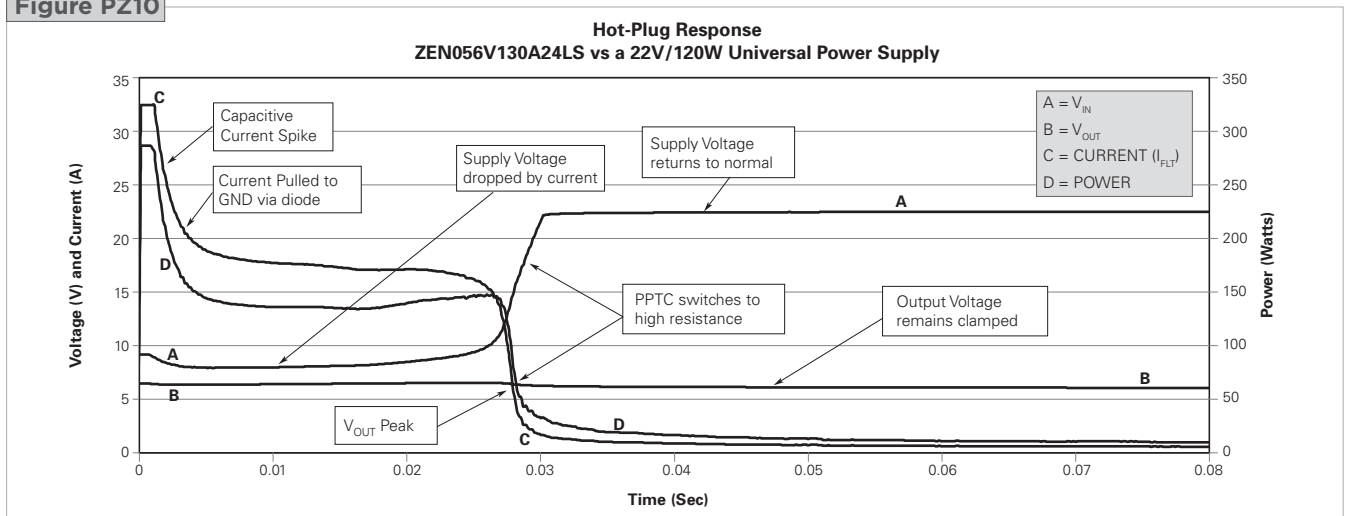


Figure PZ11

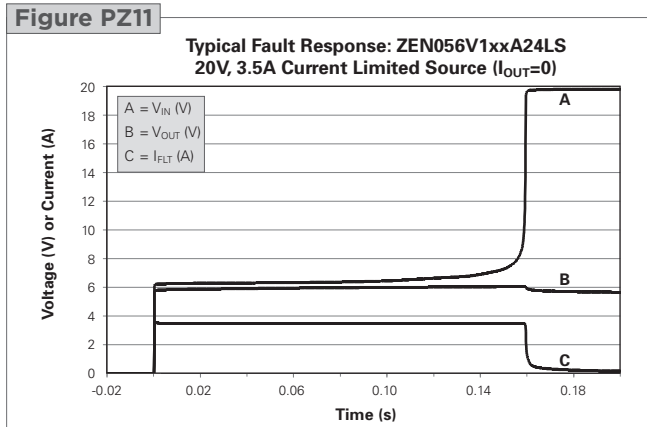


Figure PZ12

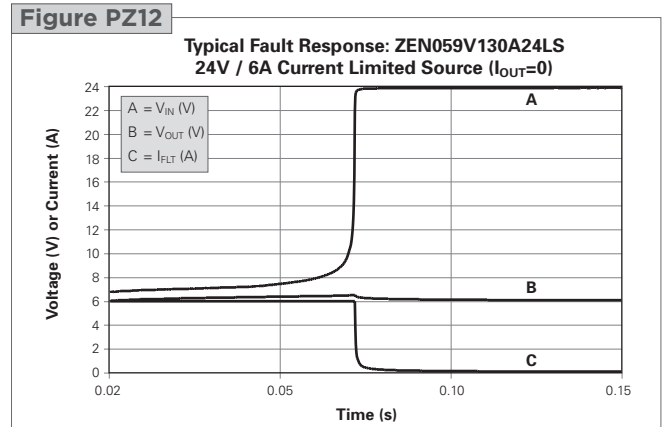


Figure PZ13

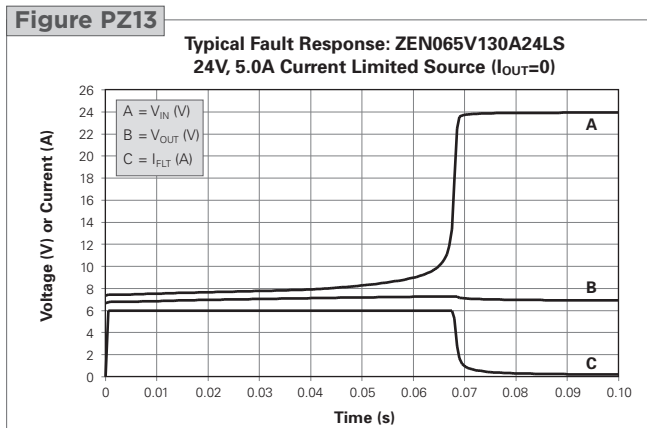


Figure PZ14

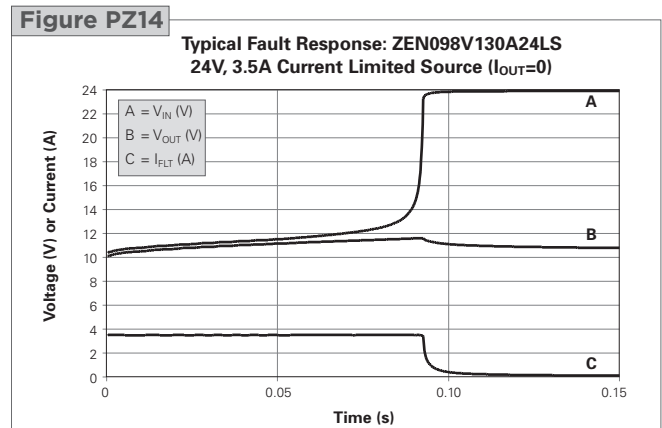


Figure PZ16-PZ23 Basic Operation Examples for PolyZen Devices

Cont'd

Figure PZ15

Typical Fault Response: ZEN132V130A24LS
24V, 2.0A Current Limited Source ($I_{OUT}=0$)

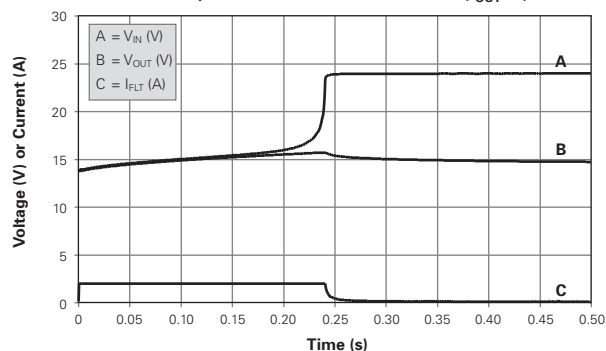


Figure PZ16

Typical Fault Response: ZEN164V130A24LS
24V, 1.0A Current Limited Source ($I_{OUT}=0$)

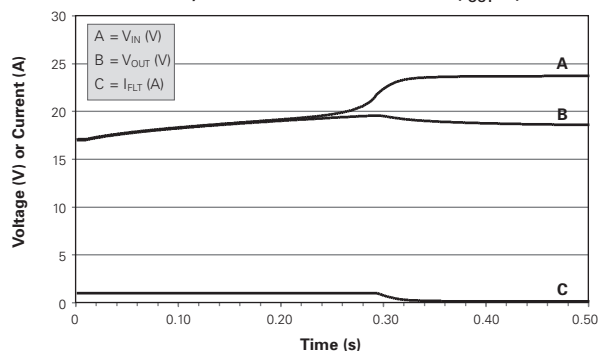


Figure PZ17

Typical Fault Response: ZEN056V230A16LS
16V, 5.0A Current Limited Source ($I_{OUT}=0$)

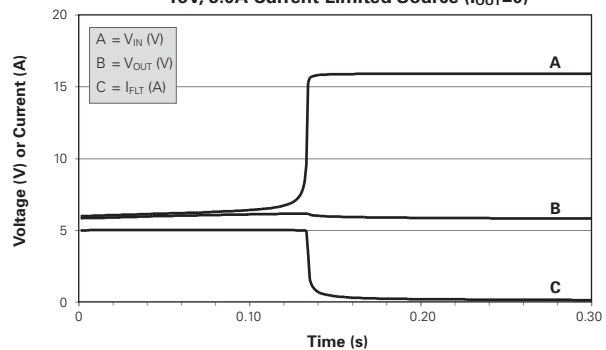


Figure PZ18

Typical Fault Response: ZEN065V230A16LS
16V, 3.5A Current Limited Source ($I_{OUT}=0$)

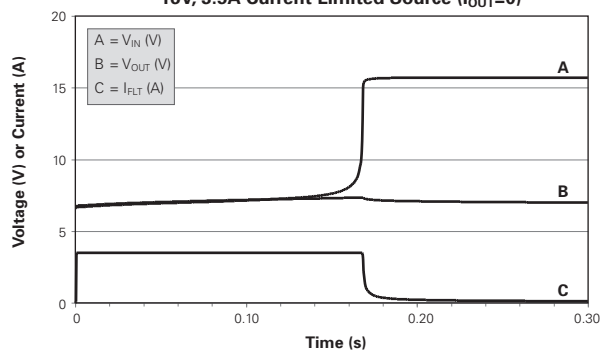


Figure PZ19

Typical Fault Response: ZEN098V230A16LS
16V, 3.5A Current Limited Source ($I_{OUT}=0$)

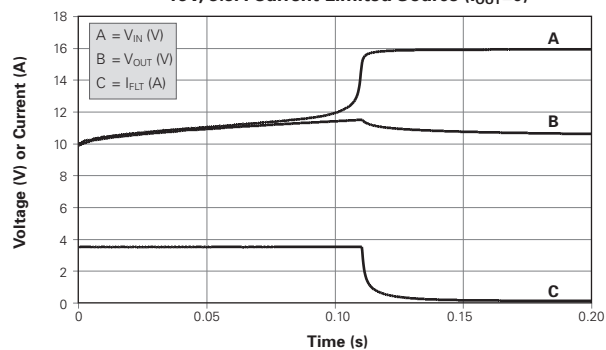


Figure PZ20

Typical Fault Response: ZEN132V230A16LS
20V, 2.0A Current Limited Source ($I_{OUT}=0$)

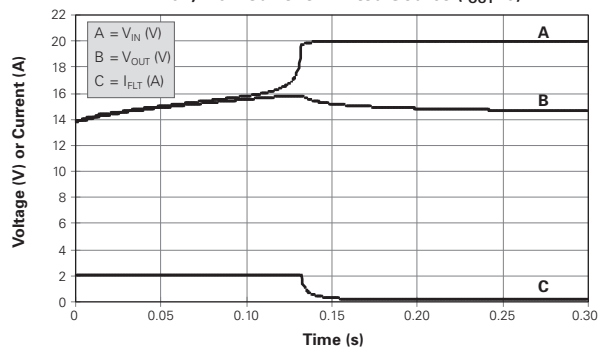


Figure PZ21

Typical Fault Response: ZEN056V075A48LS
48V, 10.0A Current Limited Source ($I_{OUT}=0$)

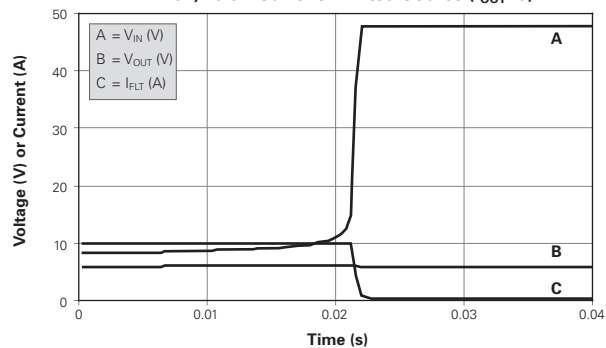
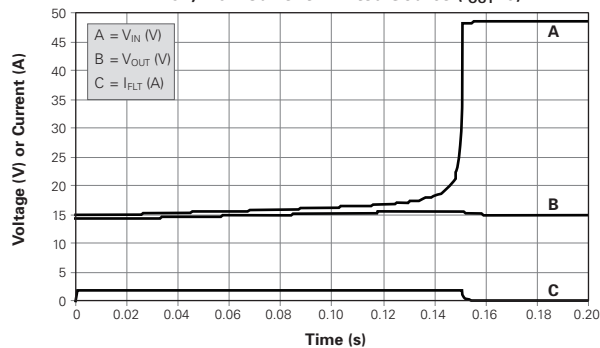


Figure PZ22

Typical Fault Response: ZEN132V075A48LS
48V, 2.0A Current Limited Source ($I_{OUT}=0$)



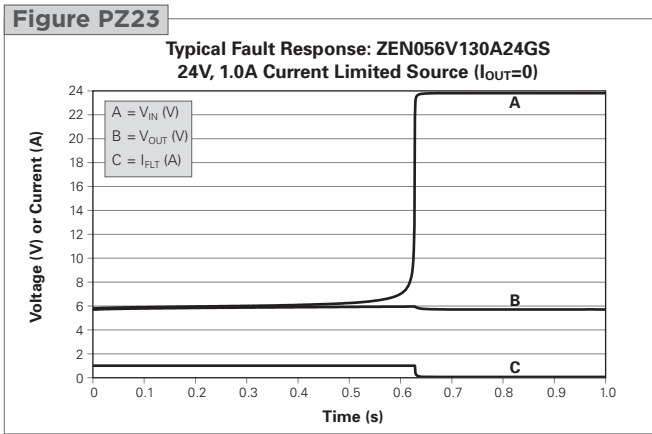


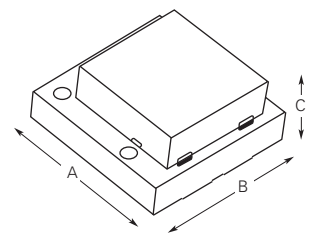
Table PZ4 Packaging and Marking Information for PolyZen Devices

Part Number	Bag Quantity	Tape & Reel Quantity	Standard Package
ZENxxxVyyyAzzLS	-	3,000	15,000
ZENxxxVyyyAzzGS	-	4,000	20,000

Table PZ5 Dimensions for PolyZen Devices in Millimeters (Inches)

ZENxxxVyyyAzzLS Devices

	A		B		C	
	Min.	Max.	Min.	Max.	Min.	Max.
mm	3.85	4.15	3.85	4.15	1.40	2.00
inch	(0.152)	(0.163)	(0.152)	(0.163)	(0.055)	(0.081)



ZENxxxVyyyAzzGS Devices

	L		W		H	
	Min.	Max.	Min.	Max.	Min.	Max.
mm	3.85	4.15	3.85	4.15	1.16	1.25
inch	(0.152)	(0.163)	(0.152)	(0.163)	(0.046)	(0.049)

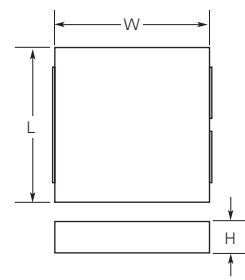
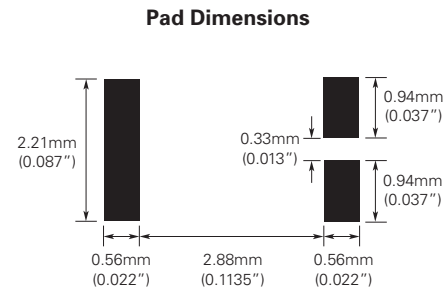
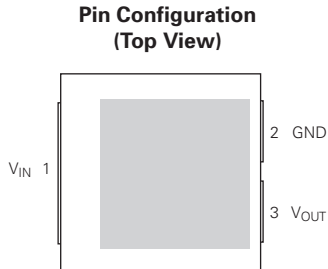


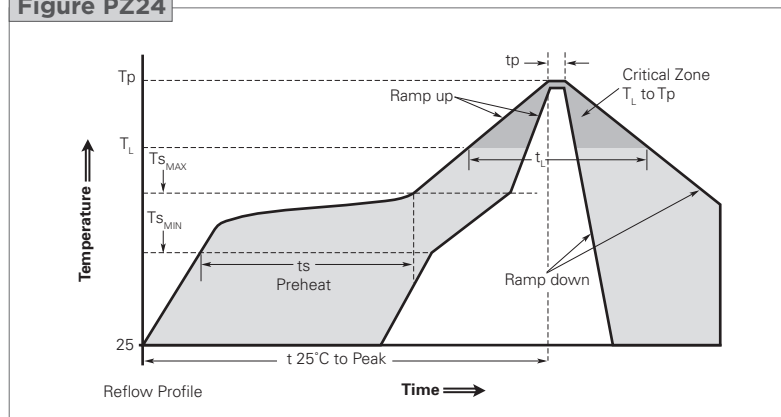
Table PZ6 Pad Layout and Configuration Information for PolyZen Devices

Pin Number	Pin Name	Pin Function
1	V_{IN}	V_{IN} = Protected input to Zener diode
2	GND	GND = Ground
3	V_{OUT}	V_{OUT} = Zener regulated voltage output


Solder Reflow and Rework Recommendation for PolyZen Devices
Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average ramp up rate ($T_{S_{MAX}}$ to T_p)	3°C/second max.
Preheat	
• Temperature min. ($T_{S_{MIN}}$)	150°C
• Temperature max. ($T_{S_{MAX}}$)	200°C
• Time ($t_{S_{MIN}}$ to $t_{S_{MAX}}$)	60-180 seconds
Time maintained above:	
• Temperature (T_L)	217°C
• Time (t_L)	60-150 seconds
Peak/Classification temperature (T_p)	260°C
Time within 5°C of actual peak temperature	
Time (t_p)	20-40 seconds
Ramp down rate	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

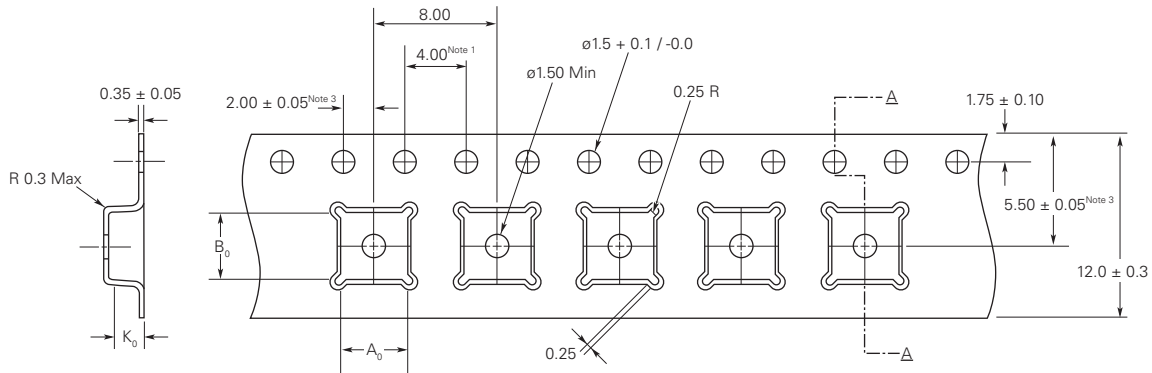
Note: All temperatures refer to topside of the package, measured on the package body surface.

Figure PZ24


Tape and Reel Specifications for PolyZen Devices (in Millimeters)

Figure PZ25 EIA Referenced Taped Component Dimensions for PolyZen Devices (in Millimeters)

Description	ZENxxxVyyyAzzLS Devices	ZENxxxVyyyAzzGS Devices
A ₀	4.35	4.35
B ₀	4.35	4.35
K ₀	2.30	1.80

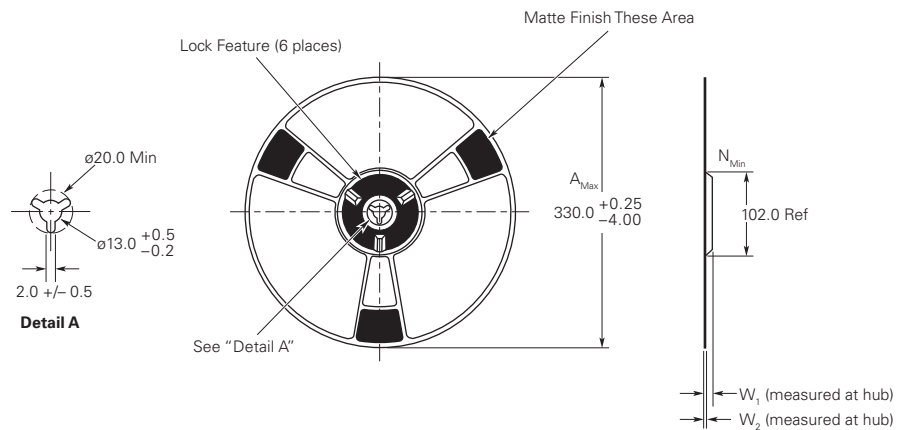


Notes:

1. 10 sprocket hole pitch cumulative tolerance ±0.2
2. Camber in compliance with EIA 481
3. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole

Figure PZ26 Reel Dimensions for PolyZen Devices (in Millimeters)

Description	Dimension (mm)
A _{Max}	330
N _{Min}	102
W ₁	8.4
W ₂	11.1



Part Numbering System for PolyZen Devices

ZEN 056V 130A 24 LS & GS

Special Labeling

LS = Module Height of 2.0mm
GS = Module Height of 1.25mm

V_{INT} Max Rating (24 = 24V)

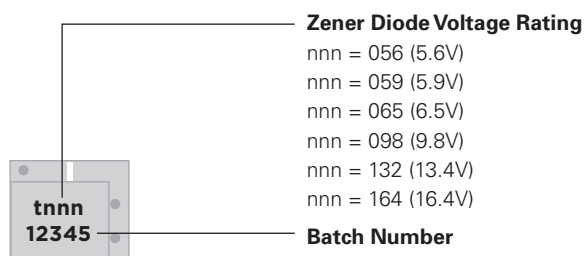
PPTC Hold Current Group (130 = 1.3A)

Zener Voltage Group (056 = 5.6V)

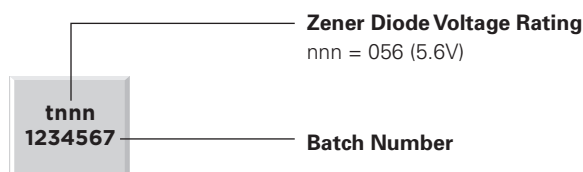
PolyZen Series

Part Marking System for PolyZen Devices

ZENxxxVyyyAzzLS Devices



ZENxxxVyyyAzzGS Devices



Warning :

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